

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application.

LISTING OF CLAIMS:

1. (Currently Amended) A component, comprising:
a functional layer;
a surface micromechanical structure produced in the functional layer and including movable elements and immovable elements;
at least one electrically non-conductive first insulation layer;
at least one first sacrificial layer; and
a substrate to which is connected the functional layer via the at least one electrically non-conductive first insulation layer and the at least one first sacrificial layer,
wherein:
the movable elements are exposed by partially removing the at least one first sacrificial layer in the area of the movable elements, ~~and~~
the at least one electrically non-conductive first insulation layer includes a material that is substantially not attacked in the removing of the at least one first sacrificial layer, and
the component is configured to perform an intended functionality of the component.
2. (Previously Presented) The component as recited in Claim 1, further comprising:
an electroconductive layer that is structured and that is contactingly situated vertically between the at least one electrically non-conductive first insulation layer and the at least one first sacrificial layer.
3. (Original) The component as recited in Claim 1, further comprising:
at least one membrane layer arranged over the surface micromechanical structure, the at least one membrane layer being mechanically connected to the substrate via at least one of the immovable elements;
at least one second sacrificial layer arranged between the functional layer and the at

least one membrane layer; and

at least one second insulation layer arranged between the at least one of the immovable elements and the at least one membrane layer, wherein:

the movable elements are exposed by removing the at least one second sacrificial layer, and

the at least one second insulation layer includes a material that is not substantially attacked by the removing of the at least one second sacrificial layer.

4. (Original) The component as recited in Claim 3, wherein:

the at least one electrically non-conductive first insulation layer and the at least one second insulation layer are located only in areas of the immovable elements.

5. (Currently Amended) The component as recited in Claim 1, wherein:

the at least one first sacrificial layer is not present ~~removed at least in a first area~~[[s]] of the immovable elements, and

the functional layer in the first area[[s]] ~~of the immovable elements where the at least one sacrificial layer is removed~~ is in direct contact with a layer which is situated underneath the at least one first sacrificial layer in a second area.

6. (Original) The component as recited in Claim 3, wherein:

the at least one second sacrificial layer is removed at least in areas of the immovable elements, and

the at least one membrane layer in the areas is in direct contact with the at least one second insulation layer.

7. (Original) The component as recited in Claim 3, wherein:

the at least one of the immovable elements includes at least one electrode, and
the at least one electrode is electrically contactable via the at least one membrane layer in that the at least one second insulation layer has at least one contact hole in an area of the at least one electrode through which the at least one membrane layer is in direct contact with the at least one electrode.

8. (Previously Presented) The component as recited in Claim 3, wherein:

the at least one first sacrificial layer and the at least one second sacrificial layer include silicon oxide, the silicon oxide being removed using an HF etching medium, and

the at least one electrically non-conductive first insulation layer and the at least one second insulation layer include one of silicon nitride and silicon carbide.

9. (Original) The component as recited in Claim 3, wherein:

the at least one electrically non-conductive first insulation layer and the at least one second insulation layer include silicon nitride having a silicon content greater than 42%.

10-19. (Cancelled)

20. (Currently Amended) A component, comprising:

a functional layer;

a surface micromechanical structure produced in the functional layer and including movable elements and immovable elements;

at least one electrically non-conductive first insulation layer;

at least one first sacrificial layer; and

a substrate to which is connected the functional layer via the at least one electrically non-conductive first insulation layer and the at least one first sacrificial layer,

wherein:

the movable elements are exposed by partially removing the at least one first sacrificial layer in the area of the movable elements,

the at least one electrically non-conductive first insulation layer includes a material that is substantially not attacked in the removing of the at least one first sacrificial layer, and

the component includes at least one area where:

the at least one electrically non-conductive first insulation layer is arranged over the substrate;

a conductive layer is arranged over the at least one electrically non-conductive first insulation layer; and

the at least one first sacrificial layer is arranged over the conductive layer, and

the component is configured to perform an intended functionality of the component.

21. (New) The component of claim 1, wherein the component comprises a sensor and the intended functionality includes sensing by the sensor.

22. (New) The component of claim 20, wherein the component comprises a sensor and the intended functionality includes sensing by the sensor.